

## FEATURES

- Member of the Texas Instruments Widebus™ Family
- DOC™ Circuitry Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With  $I_{OH}$  and  $I_{OL}$  of  $\pm 24$  mA at 2.5-V  $V_{CC}$
- Control Inputs  $V_{IH}/V_{IL}$  Levels Are Referenced to  $V_{CCB}$  Voltage
- If Either  $V_{CC}$  Input Is at GND, Both Ports Are in the High-Impedance State
- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over Full 1.4-V to 3.6-V Power-Supply Range
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## DESCRIPTION

This 16-bit (dual-octal) noninverting bus transceiver uses two separate configurable power-supply rails. The A port is designed to track  $V_{CCA}$ .  $V_{CCA}$  accepts any supply voltage from 1.4 V to 3.6 V. The B port is designed to track  $V_{CCB}$ .  $V_{CCB}$  accepts any supply voltage from 1.4 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

The SN74AVCB164245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the outputs so the buses are effectively isolated.

The SN74AVCB164245 is designed so that the control pins (1DIR, 2DIR,  $1\overline{OE}$ , and  $2\overline{OE}$ ) are supplied by  $V_{CCB}$ .

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CCB}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. If either  $V_{CC}$  input is at GND, both ports are in the high-impedance state.

## ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	FBGA – GRD	Tape and reel	74AVCB164245GRDR	WB4245
	FBGA – ZRD (Pb-Free)	Tape and reel	74AVCB164245ZRDR	
	TSSOP – DGG	Tape and reel	SN74AVCB164245GR	AVCB164245
	TVSOP – DGV	Tape and reel	SN74AVCB164245VR	WB4245
	VFBGA – GQL	Tape and reel	SN74AVCB164245KR	
	VFBGA – ZQL (Pb-Free)	Tape and reel	74AVCB164245ZQLR	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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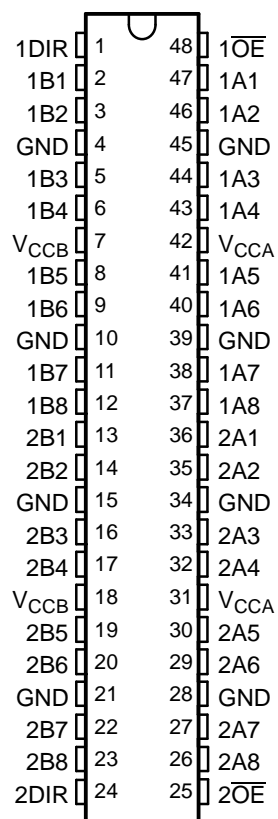
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**SN74AVCB164245**  
**16-BIT DUAL-SUPPLY BUS TRANSCEIVER**  
**WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS**

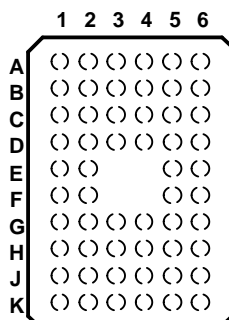
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**TERMINAL ASSIGNMENTS**

**DGG OR DGV PACKAGE**  
**(TOP VIEW)**



**GQL OR ZQL PACKAGE  
(TOP VIEW)**

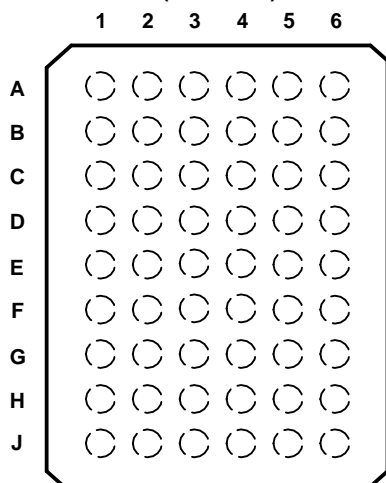


**TERMINAL ASSIGNMENTS  
(56-Ball GQL/ZQL Package)<sup>(1)</sup>**

	1	2	3	4	5	6
<b>A</b>	1DIR	NC	NC	NC	NC	1 $\overline{OE}$
<b>B</b>	1B2	1B1	GND	GND	1A1	1A2
<b>C</b>	1B4	1B3	V <sub>CCB</sub>	V <sub>CCA</sub>	1A3	1A4
<b>D</b>	1B6	1B5	GND	GND	1A5	1A6
<b>E</b>	1B8	1B7			1A7	1A8
<b>F</b>	2B1	2B2			2A2	2A1
<b>G</b>	2B3	2B4	GND	GND	2A4	2A3
<b>H</b>	2B5	2B6	V <sub>CCB</sub>	V <sub>CCA</sub>	2A6	2A5
<b>J</b>	2B7	2B8	GND	GND	2A8	2A7
<b>K</b>	2DIR	NC	NC	NC	NC	2 $\overline{OE}$

(1) NC - No internal connection

**GRD OR ZRD PACKAGE  
(TOP VIEW)**



**TERMINAL ASSIGNMENTS  
(54-Ball GRD/ZRD Package)<sup>(1)</sup>**

	1	2	3	4	5	6
<b>A</b>	1B1	NC	1DIR	1 $\overline{OE}$	NC	1A1
<b>B</b>	1B3	1B2	NC	NC	1A2	1A3
<b>C</b>	1B5	1B4	V <sub>CCB</sub>	V <sub>CCA</sub>	1A4	1A5
<b>D</b>	1B7	1B6	GND	GND	1A6	1A7
<b>E</b>	2B1	1B8	GND	GND	1A8	2A1
<b>F</b>	2B3	2B2	GND	GND	2A2	2A3
<b>G</b>	2B5	2B4	V <sub>CCB</sub>	V <sub>CCA</sub>	2A4	2A5
<b>H</b>	2B7	2B6	NC	NC	2A6	2A7
<b>J</b>	2B8	NC	2DIR	2 $\overline{OE}$	NC	2A8

(1) NC - No internal connection

**FUNCTION TABLE  
(EACH 8-BIT SECTION)**

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

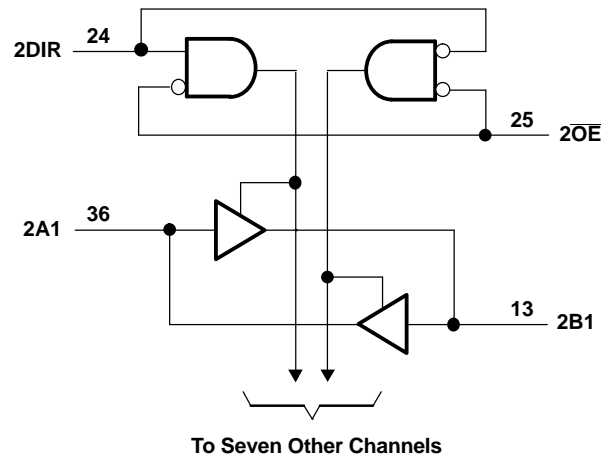
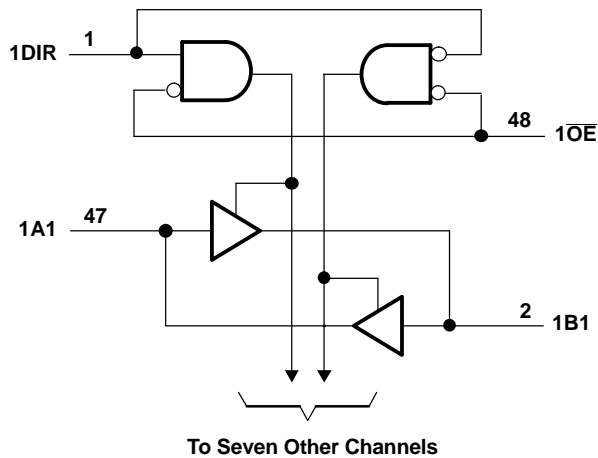
# SN74AVCB164245

## 16-BIT DUAL-SUPPLY BUS TRANSCEIVER

### WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS

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**LOGIC DIAGRAM (POSITIVE LOGIC)**



Pin numbers shown are for the DGG and DGV packages.

### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CCA}$ $V_{CCB}$	Supply voltage range		−0.5	4.6	V
$V_I$	Input voltage range <sup>(2)</sup>	I/O ports (A port)	−0.5	4.6	V
		I/O ports (B port)	−0.5	4.6	
		Control inputs	−0.5	4.6	
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	A port	−0.5	4.6	V
		B port	−0.5	4.6	
$V_O$	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	A port	−0.5	$V_{CCA} + 0.5$	V
		B port	−0.5	$V_{CCB} + 0.5$	
$I_{IK}$	Input clamp current	$V_I < 0$		−50	mA
$I_{OK}$	Output clamp current	$V_O < 0$		−50	mA
$I_O$	Continuous output current			50	mA
	Continuous current through $V_{CCA}$ , $V_{CCB}$ , or GND			100	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DGG package		70	°C/W
		DGV package		58	
		GQL/ZQL package		28	
		GRD/ZRD package		36	
$T_{stg}$	Storage temperature range		−65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

### Recommended Operating Conditions<sup>(1)(2)(3)</sup>

over operating free-air temperature range (unless otherwise noted)

			V <sub>CCI</sub>	V <sub>CCO</sub>	MIN	MAX	UNIT
V <sub>CCA</sub>	Supply voltage				1.4	3.6	V
V <sub>CCB</sub>	Supply voltage				1.4	3.6	V
V <sub>IH</sub>	High-level input voltage	Data inputs	1.4 V to 1.95 V		V <sub>CCI</sub> × 0.65		V
			1.95 V to 2.7 V		1.7		
			2.7 V to 3.6 V		2		
V <sub>IL</sub>	Low-level input voltage	Data inputs	1.4 V to 1.95 V		V <sub>CCI</sub> × 0.35		V
			1.95 V to 2.7 V		0.7		
			2.7 V to 3.6 V		0.8		
V <sub>IH</sub>	High-level input voltage	Control inputs (referenced to V <sub>CCB</sub> )	1.4 V to 1.95 V		V <sub>CCB</sub> × 0.65		V
			1.95 V to 2.7 V		1.7		
			2.7 V to 3.6 V		2		
V <sub>IL</sub>	Low-level input voltage	Control inputs (referenced to V <sub>CCB</sub> )	1.4 V to 1.95 V		V <sub>CCB</sub> × 0.35		V
			1.95 V to 2.7 V		0.7		
			2.7 V to 3.6 V		0.8		
V <sub>I</sub>	Input voltage				0	3.6	V
V <sub>O</sub>	Output voltage	Active state			0	V <sub>CCO</sub>	V
		3-state			0	3.6	
I <sub>OH</sub>	High-level output current			1.4 V to 1.6 V	−2		mA
				1.65 V to 1.95 V	−4		
				2.3 V to 2.7 V	−8		
				3 V to 3.6 V	−12		
I <sub>OL</sub>	Low-level output current			1.4 V to 1.6 V	2		mA
				1.65 V to 1.95 V	4		
				2.3 V to 2.7 V	8		
				3 V to 3.6 V	12		
Δt/Δv	Input transition rise or fall rate				5		ns/V
T <sub>A</sub>	Operating free-air temperature				−40	85	°C

(1)  $V_{CCI}$  is the  $V_{CC}$  associated with the data input port.

(2)  $V_{CCO}$  is the  $V_{CC}$  associated with the data output port.

(3) All unused data inputs of the device must be held at  $V_{CCI}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**Electrical Characteristics**<sup>(1)(2)</sup>

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	TYP <sup>(3)</sup>	MAX	UNIT
V <sub>OH</sub>		I <sub>OH</sub> = −100 μA	V <sub>I</sub> = V <sub>IH</sub>	1.4 V to 3.6 V	1.4 V to 3.6 V	V <sub>CCO</sub> − 0.2			V
		I <sub>OH</sub> = −2 mA	V <sub>I</sub> = V <sub>IH</sub>	1.4 V	1.4 V	1.05			
		I <sub>OH</sub> = −4 mA	V <sub>I</sub> = V <sub>IH</sub>	1.65 V	1.65 V	1.2			
		I <sub>OH</sub> = −8 mA	V <sub>I</sub> = V <sub>IH</sub>	2.3 V	2.3 V	1.75			
		I <sub>OH</sub> = −12 mA	V <sub>I</sub> = V <sub>IH</sub>	3 V	3 V	2.3			
V <sub>OL</sub>		I <sub>OH</sub> = 100 μA	V <sub>I</sub> = V <sub>IL</sub>	1.4 V to 3.6 V	1.4 V to 3.6 V	0.2			V
		I <sub>OH</sub> = 2 mA	V <sub>I</sub> = V <sub>IL</sub>	1.4 V	1.4 V	0.35			
		I <sub>OH</sub> = 4 mA	V <sub>I</sub> = V <sub>IL</sub>	1.65 V	1.65 V	0.45			
		I <sub>OH</sub> = 8 mA	V <sub>I</sub> = V <sub>IL</sub>	2.3 V	2.3 V	0.55			
		I <sub>OH</sub> = 12 mA	V <sub>I</sub> = V <sub>IL</sub>	3 V	3 V	0.7			
I <sub>I</sub>	Control inputs	V <sub>I</sub> = V <sub>CCB</sub> or GND		1.4 V to 3.6 V	3.6 V	±2.5			μA
I <sub>off</sub>	A port	V <sub>I</sub> or V <sub>O</sub> = 0 to 3.6 V		0 V	0 to 3.6 V	±10			μA
	B port			0 to 3.6 V	0 V	±10			
I <sub>OZ</sub> <sup>(4)</sup>	A or B ports	V <sub>O</sub> = V <sub>CCO</sub> or GND, V <sub>I</sub> = V <sub>CCI</sub> or GND	$\overline{OE}$ = V <sub>IH</sub>	3.6 V	3.6 V	±12.5			μA
	B port		$\overline{OE}$ = don't care	0 V	3.6 V	±12.5			
	A port		$\overline{OE}$ = don't care	3.6 V	0 V	±12.5			
I <sub>CCA</sub>	V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0			1.6 V	1.6 V	20			μA
				1.95 V	1.95 V	20			
				2.7 V	2.7 V	30			
				0 V	3.6 V	−40			
				3.6 V	0 V	40			
				3.6 V	3.6 V	40			
I <sub>CCB</sub>	V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0			1.6 V	1.6 V	20			μA
				1.95 V	1.95 V	20			
				2.7 V	2.7 V	30			
				0 V	3.6 V	40			
				3.6 V	0 V	−40			
				3.6 V	3.6 V	40			
C <sub>i</sub>	Control inputs	V <sub>I</sub> = 3.3 V or GND		3.3 V	3.3 V	4			pF
C <sub>io</sub>	A or B ports	V <sub>O</sub> = 3.3 V or GND		3.3 V	3.3 V	5			pF

(1) V<sub>CCO</sub> is the V<sub>CC</sub> associated with the output port.(2) V<sub>CCI</sub> is the V<sub>CC</sub> associated with the input port.(3) All typical values are at T<sub>A</sub> = 25°C.(4) For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CCA} = 1.5 \text{ V} \pm 0.1 \text{ V}$  (see [Figure 2](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.5 \text{ V}$ 0.1 V		$V_{CCB} = 1.8 \text{ V}$ 0.15 V		$V_{CCB} = 2.5 \text{ V}$ 0.2 V		$V_{CCB} = 3.3 \text{ V}$ 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	1.7	6.7	1.9	6.3	1.8	5.5	1.7	5.8	ns
	B	A	1.8	6.8	2.2	7.4	2.1	7.6	2.1	7.3	
$t_{en}$	$\overline{OE}$	A	2.5	8.4	2.4	7.4	2.1	5.2	1.9	4.2	ns
		B	2.1	9	2.9	9.8	3.2	10	3	9.8	
$t_{dis}$	$\overline{OE}$	A	2.2	6.9	2.3	6.1	1.3	3.6	1.3	3	ns
		B	2.1	7.1	2.3	6.4	1.7	5.1	1.6	4.8	

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$  (see [Figure 2](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.5 \text{ V}$ 0.1 V		$V_{CCB} = 1.8 \text{ V}$ 0.15 V		$V_{CCB} = 2.5 \text{ V}$ 0.2 V		$V_{CCB} = 3.3 \text{ V}$ 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	1.7	6.7	1.8	6	1.7	4.7	1.6	4.3	ns
	B	A	1.4	5.5	1.8	6	1.8	5.8	1.8	5.5	
$t_{en}$	$\overline{OE}$	A	2.6	8.5	2.5	7.5	2.2	5.3	1.9	4.2	ns
		B	1.8	7.6	2.6	7.7	2.6	7.6	2.6	7.4	
$t_{dis}$	$\overline{OE}$	A	2.3	7	2.3	6.1	1.3	3.6	1.3	3	ns
		B	1.8	7	2.5	6.3	1.8	4.7	1.7	4.4	

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$  (see [Figure 2](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.5 \text{ V}$ 0.1 V		$V_{CCB} = 1.8 \text{ V}$ 0.15 V		$V_{CCB} = 2.5 \text{ V}$ 0.2 V		$V_{CCB} = 3.3 \text{ V}$ 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	1.6	6	1.8	5.6	1.5	4	1.4	3.4	ns
	B	A	1.3	4.6	1.7	4.4	1.5	4	1.4	3.7	
$t_{en}$	$\overline{OE}$	A	3.1	8.5	2.5	7.5	2.2	5.3	1.9	4.2	ns
		B	1.7	5.7	2.2	5.5	2.2	5.3	2.2	5.1	
$t_{dis}$	$\overline{OE}$	A	2.4	7	3	6.1	1.4	3.6	1.2	3	ns
		B	1.2	5.8	1.9	5	1.4	3.6	1.3	3.3	

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$  (see [Figure 2](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.5 \text{ V}$ 0.1 V		$V_{CCB} = 1.8 \text{ V}$ 0.15 V		$V_{CCB} = 2.5 \text{ V}$ 0.2 V		$V_{CCB} = 3.3 \text{ V}$ 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	1.5	5.9	1.7	5.4	1.5	3.7	1.4	3.1	ns
	B	A	1.3	4.5	1.6	3.8	1.5	3.3	1.4	3.1	
$t_{en}$	$\overline{OE}$	A	2.6	8.3	2.5	7.4	2.2	5.2	1.9	4.1	ns
		B	1.6	4.9	2	4.5	2	4.3	1.9	4.1	
$t_{dis}$	$\overline{OE}$	A	2.3	7	3	6	1.3	3.5	1.2	3.5	ns
		B	1.3	6.9	2.1	5.5	1.6	3.8	1.5	3.5	

# SN74AVCB164245

## 16-BIT DUAL-SUPPLY BUS TRANSCEIVER

### WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS

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#### Operating Characteristics

$V_{CCA}$  and  $V_{CCB} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER			TEST CONDITIONS	TYP	UNIT
$C_{pdA}$ ( $V_{CCA}$ )	Power dissipation capacitance per transceiver, A-port input, B-port output	Outputs enabled	$C_L = 0$ , $f = 10\text{ MHz}$	14	pF
		Outputs disabled		7	
	Power dissipation capacitance per transceiver, B-port input, A-port output	Outputs enabled		20	
		Outputs disabled		7	
$C_{pdB}$ ( $V_{CCB}$ )	Power dissipation capacitance per transceiver, A-port input, B-port output	Outputs enabled	$C_L = 0$ , $f = 10\text{ MHz}$	20	pF
		Outputs disabled		7	
	Power dissipation capacitance per transceiver, B-port input, A-port output	Outputs enabled		14	
		Outputs disabled		7	

#### Output Description

The DOC™ circuitry is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical  $V_{OL}$  vs  $I_{OL}$  and  $V_{OH}$  vs  $I_{OH}$  curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number SCEA006, and *Dynamic Output Control (DOC™) Circuitry Technology and Applications*, literature number SCEA009.

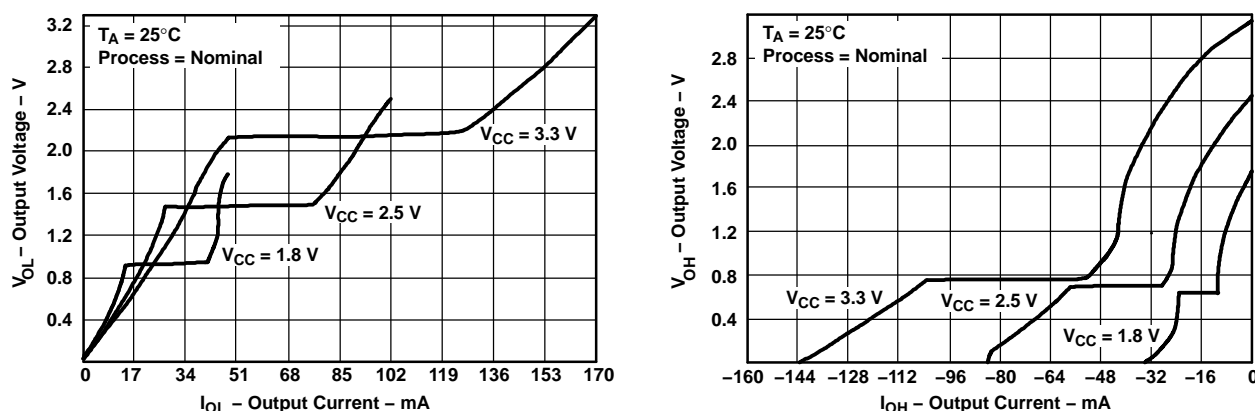
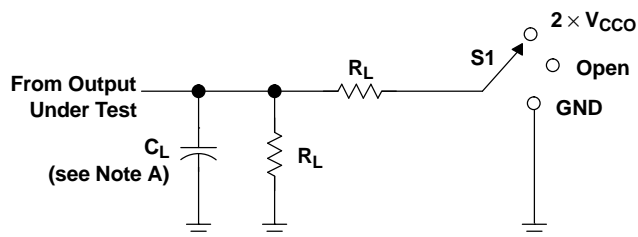


Figure 1. Typical Output Voltage vs Output Current

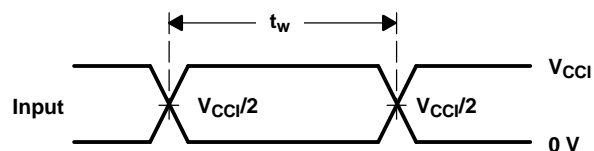
## PARAMETER MEASUREMENT INFORMATION



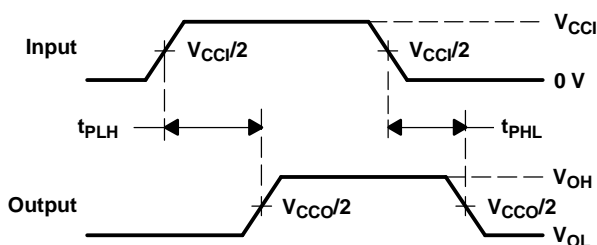
LOAD CIRCUIT

$V_{CCO}$	$C_L$	$R_L$	$V_{TP}$
$1.5\text{ V} \pm 0.1\text{ V}$	15 pF	2 k $\Omega$	0.1 V
$1.8\text{ V} \pm 0.15\text{ V}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	30 pF	500 $\Omega$	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	30 pF	500 $\Omega$	0.3 V

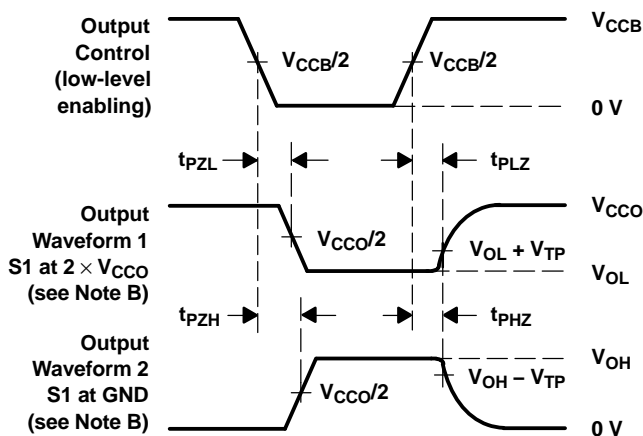
TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CCO}$
$t_{PHZ}/t_{PZH}$	GND



VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $dv/dt \geq 1\text{ V/ns}$ .
  - The outputs are measured one at a time, with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - $V_{CCI}$  is the  $V_{CC}$  associated with the input port.
  - $V_{CCO}$  is the  $V_{CC}$  associated with the output port.

Figure 2. Load Circuit and Voltage Waveforms

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74AVCB164245GRE4	Active	Production	TSSOP (DGG)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCB164245
<a href="#">SN74AVCB164245GR</a>	Active	Production	TSSOP (DGG)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCB164245
SN74AVCB164245GR.B	Active	Production	TSSOP (DGG)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVCB164245
<a href="#">SN74AVCB164245VR</a>	Active	Production	TVSOP (DGV)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WB4245
SN74AVCB164245VR.B	Active	Production	TVSOP (DGV)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WB4245
SN74AVCB164245VRG4	Active	Production	TVSOP (DGV)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WB4245
SN74AVCB164245VRG4.B	Active	Production	TVSOP (DGV)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	WB4245

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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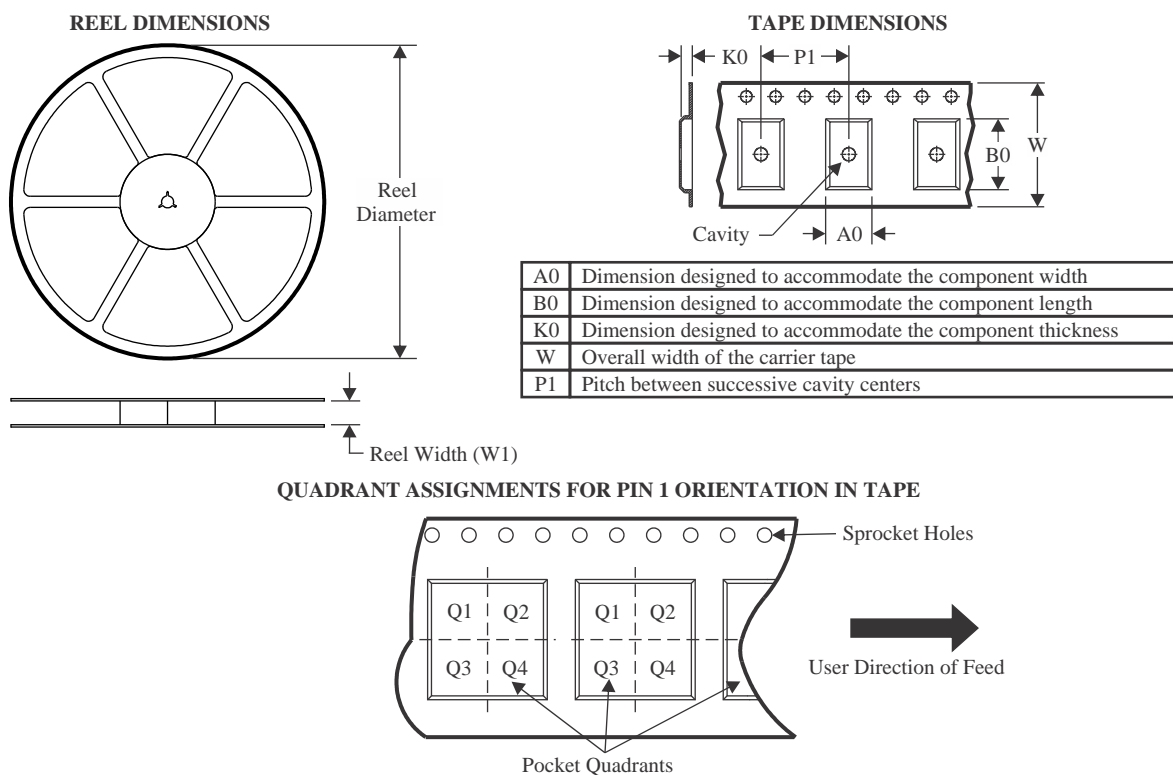
**OTHER QUALIFIED VERSIONS OF SN74AVCB164245 :**

- Automotive : [SN74AVCB164245-Q1](#)
- Enhanced Product : [SN74AVCB164245-EP](#)

**NOTE:** Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

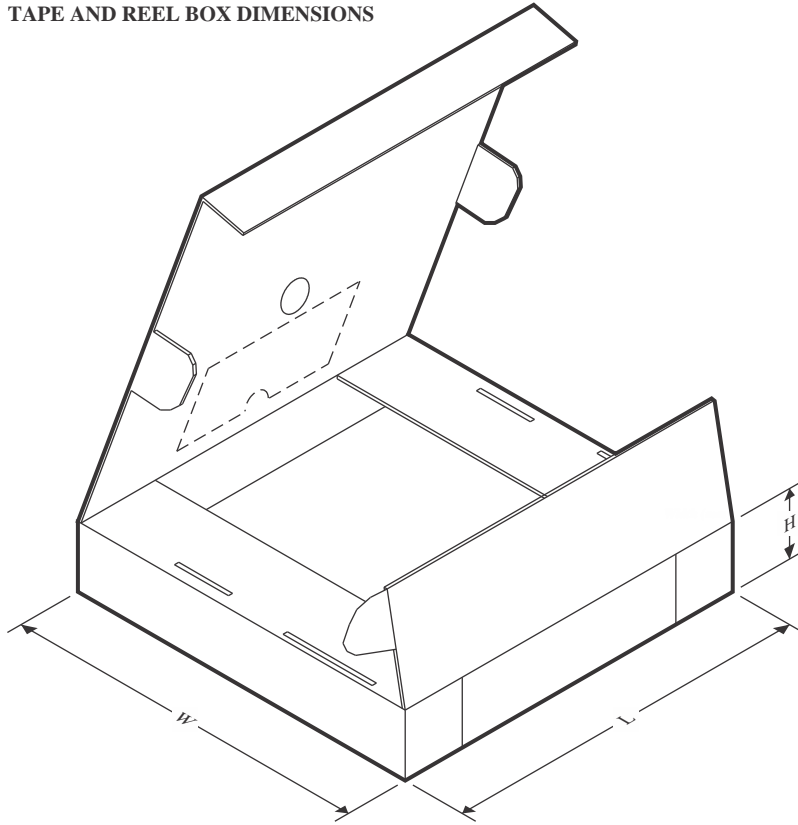
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVCB164245GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74AVCB164245VR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74AVCB164245VRG4	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



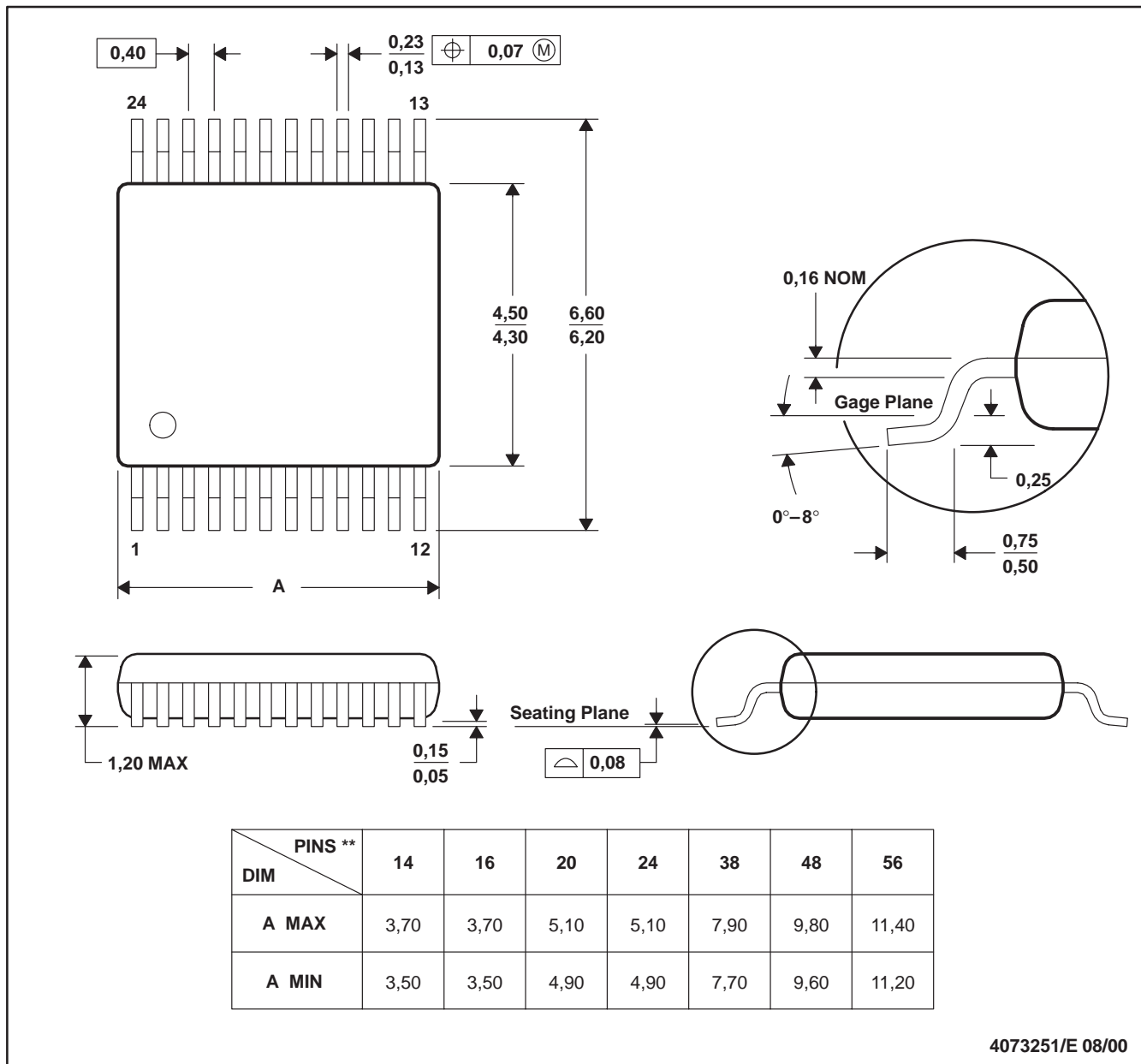
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AVCB164245GR	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74AVCB164245VR	TVSOP	DGV	48	2000	353.0	353.0	32.0
SN74AVCB164245VRG4	TVSOP	DGV	48	2000	353.0	353.0	32.0

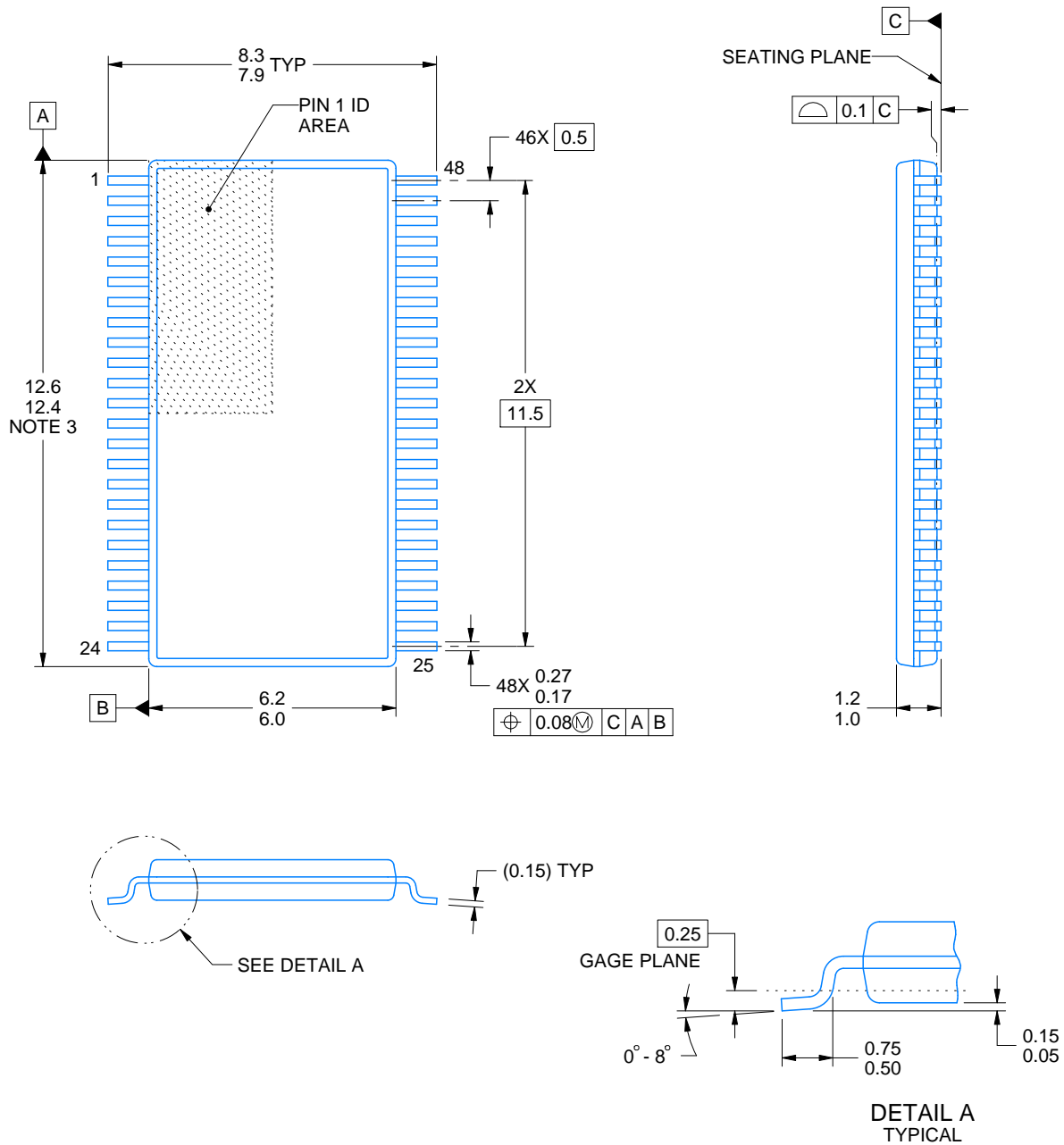
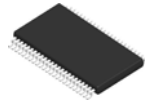
## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194



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## NOTES:

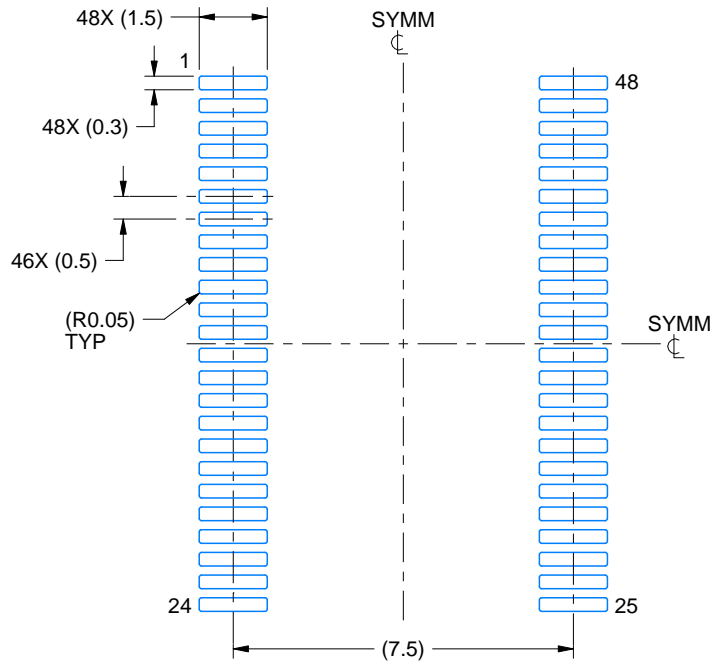
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

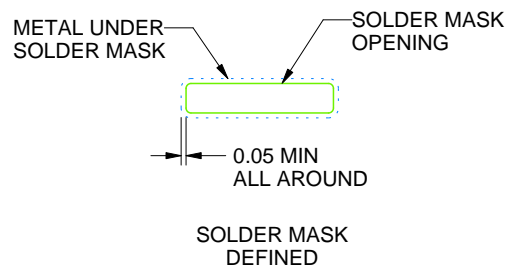
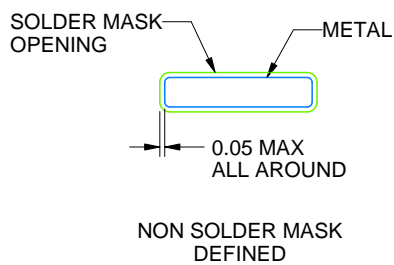
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

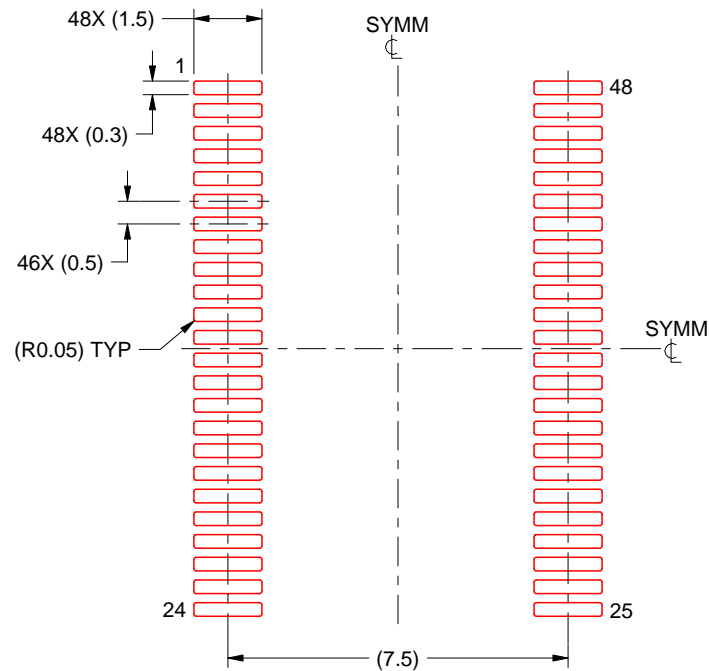
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

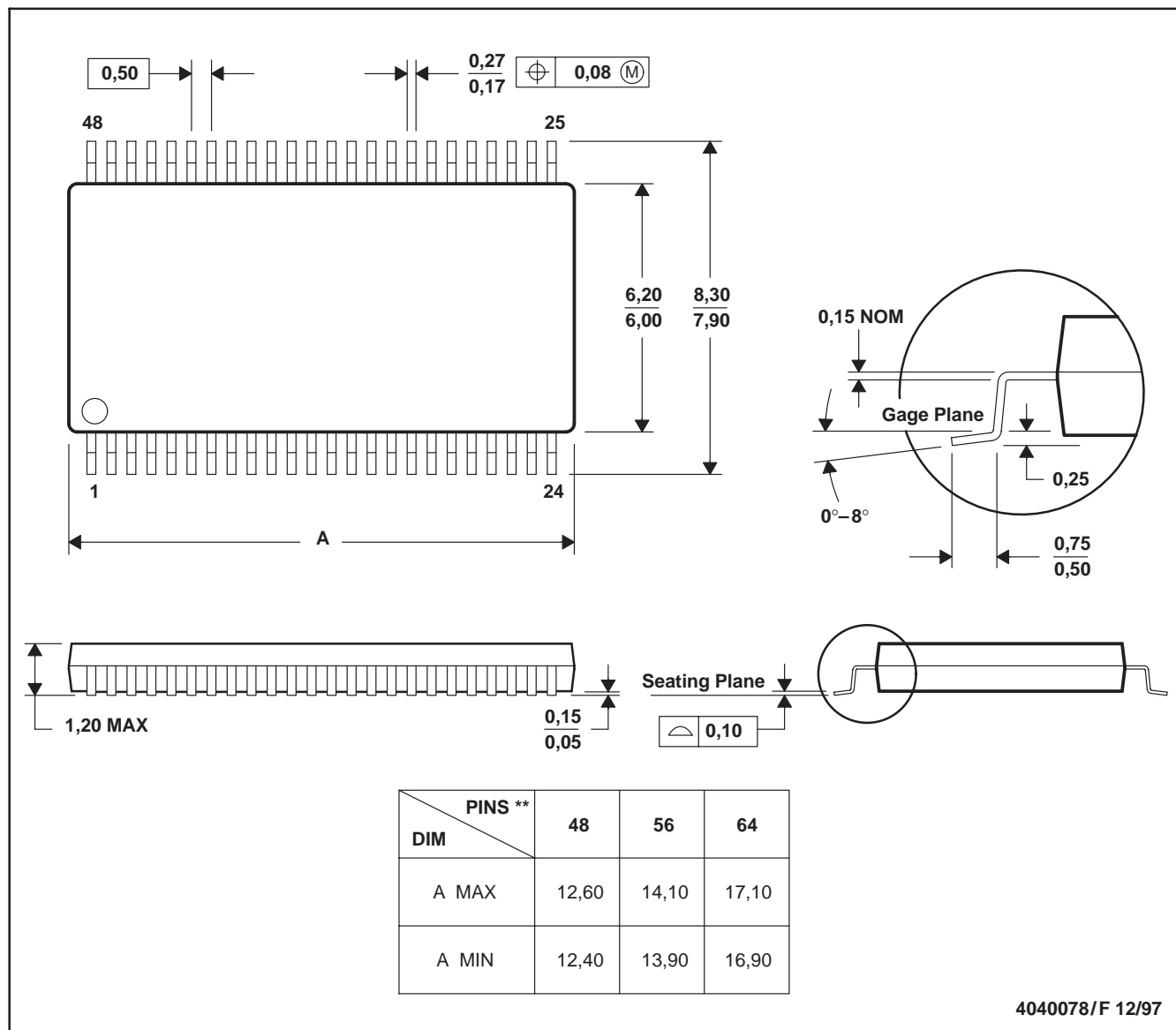


SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

**DGG (R-PDSO-G\*\*)****PLASTIC SMALL-OUTLINE PACKAGE****48 PINS SHOWN**

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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